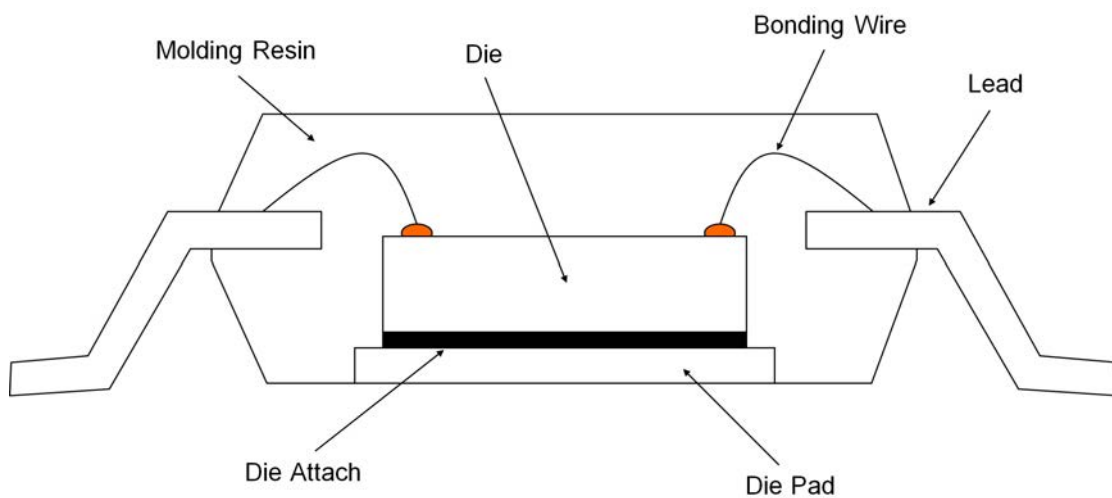


1. Package Information

Package Name	HTSOP-J8
Type	SOP
Pin Count	8
P	0.048
L	Pure Tin
MSL	Level1

2. Package Structure



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form		Tape&Reel
Packing Quantity	[pcs]	250
PIN 1 Orientation		H2

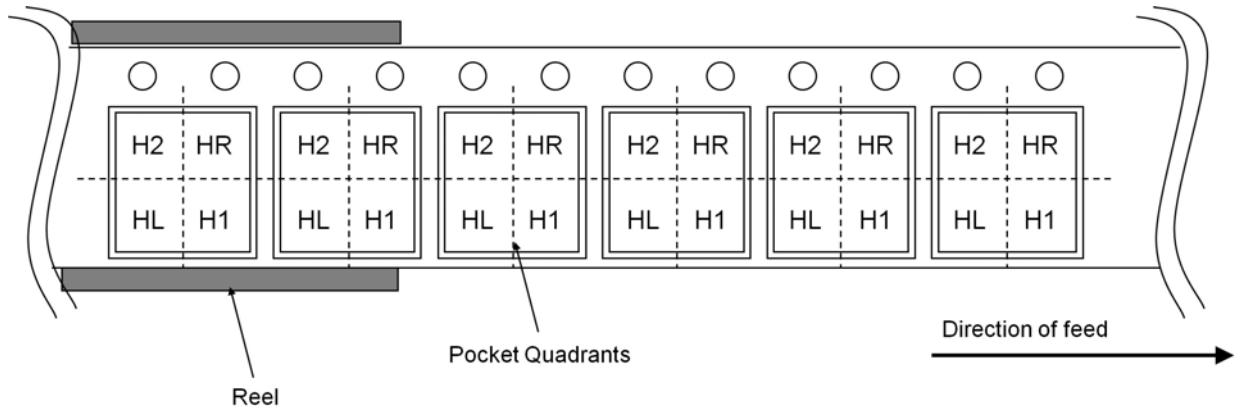


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

H2 : PIN1 is placed to the top left corner.

HR : PIN1 is placed to the top right corner.

HL : PIN1 is placed to the lower left.

H1 : PIN1 is placed to the lower right.

3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 320 mm or more.

3.4 Trailer specification

No component pockets are 80 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

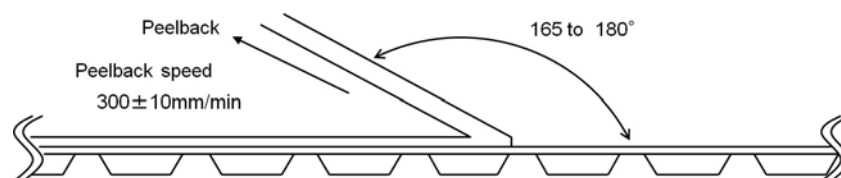


Fig. 2 Test method

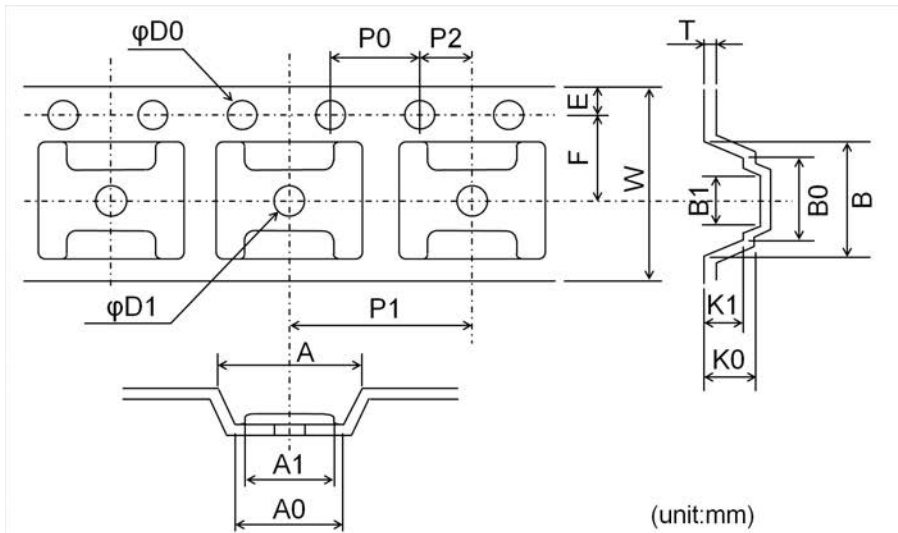
3.6 Missing lcs

(1) No consecutive dropouts.

(2) A maximum 0.1 % of specified number of products in each packing may be missing.

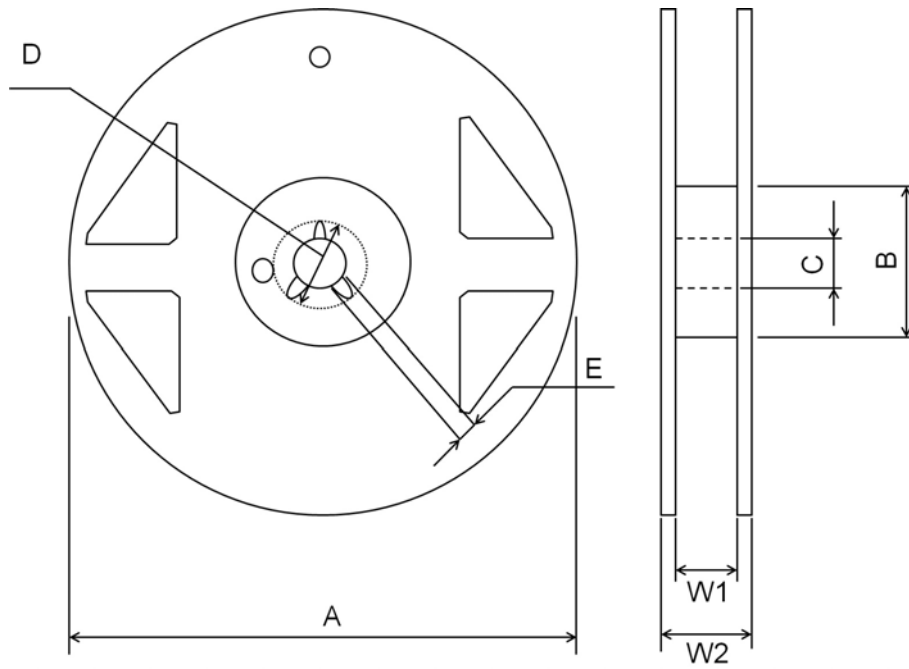
3.7 Tape and Reel Specification

3.7.1 Tape Dimension



	Tape Dimension	Tape Tolerance
A	6.45	±0.1
A0	6.3	±0.1
A1	4.00	±0.2
B	5.30	±0.1
B0	5.20	±0.1
B1	2.50	±0.2
D0	φ1.5	+0.1/-0
D1	φ1.5	+0.1/-0
E	1.75	±0.1
F	5.50	±0.05
K0	1.55	±0.1
K1	1.15	±0.1
P0	4.00	±0.1
P1	8.00	±0.1
P2	2.00	±0.05
T	0.30	±0.05
W	12.0	±0.2

3.7.2 Reel Dimension

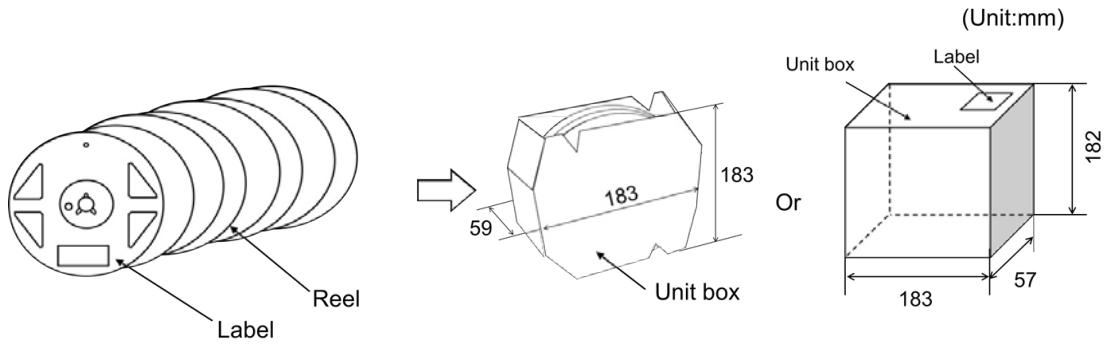


(unit:mm)

	Reel Dimension	Reel Tolerance
A	180	+0/-1.5
B	60	+1.0/-0
C	13	±0.2
D	21	±0.8
E	2	±0.5
W1	13	+1.0/-0
W2	15.4	±1.0

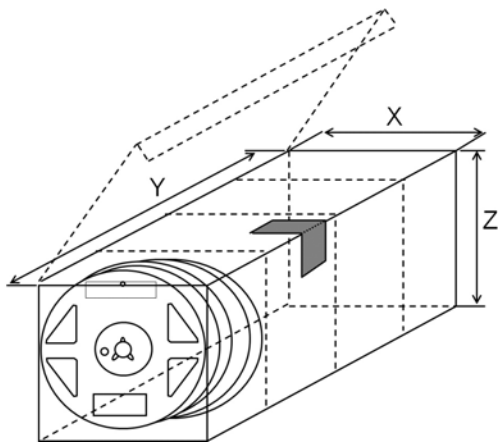
3.8 Packing Method

4 reel(s) or less per unit box



3.9 Packing Style

4 unit boxes or less per shipping box



(unit:mm)

Shipping Box Dimension	
X	190
Y	255
Z	193

3.10 Label Specification

Product No. **BD3957AEFV-CTE2** LOT No. () Outgoing inspection stamp

Quantity **2,000 pcs. 1717 A7E06H**

Internal product name **BD3957AEFV-CTE2** **K.YAMADA** FOR ROHM ONLY

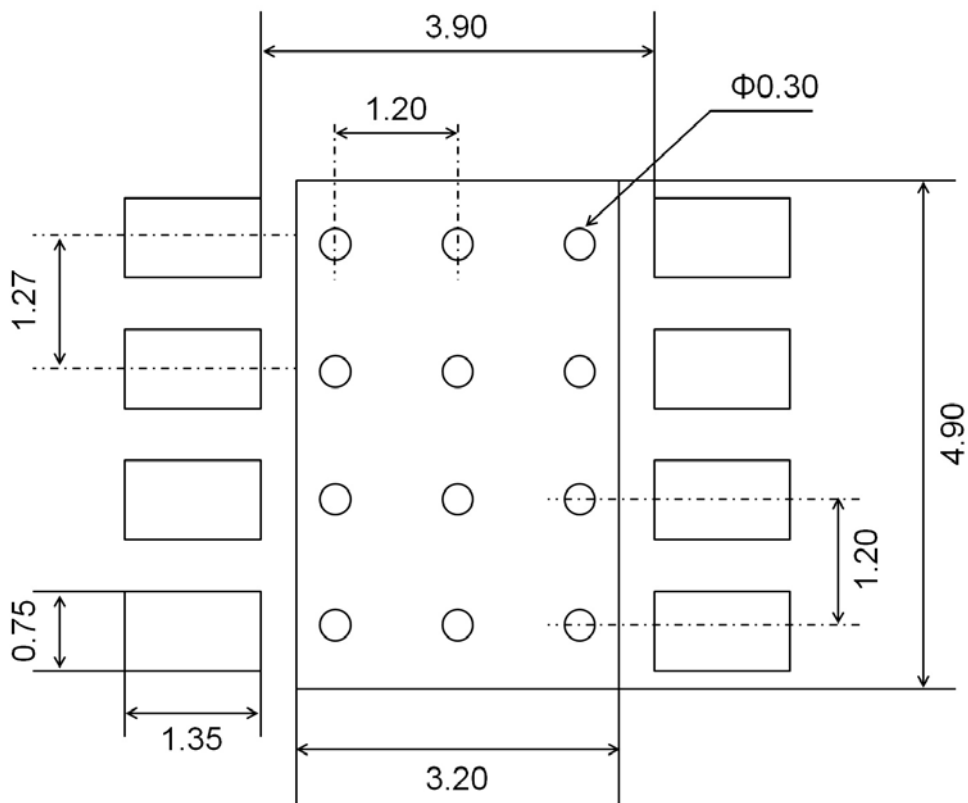
MSL3 168HRS PPBT260C Mfg No. **717 H77** pcs. **01** **Pb Free**

MADE IN PHILIPPINES **ROHM SEMICONDUCTOR** SEAL18Feb18

MSL rank, Floor life (Except MSL1 product), Package peak body temperature (PPBT) Marking lot number Bag seal date (Except MSL1 product)

Label Example

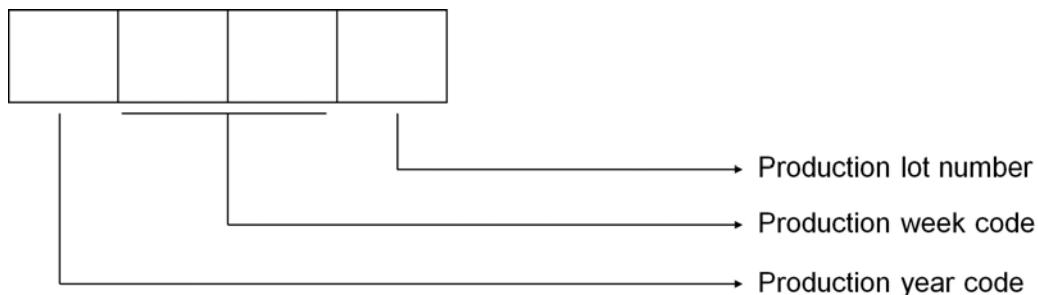
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

Recommended storage conditions

	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	-	85	% RH

6.2 Storage period (Start to count since delivery date)

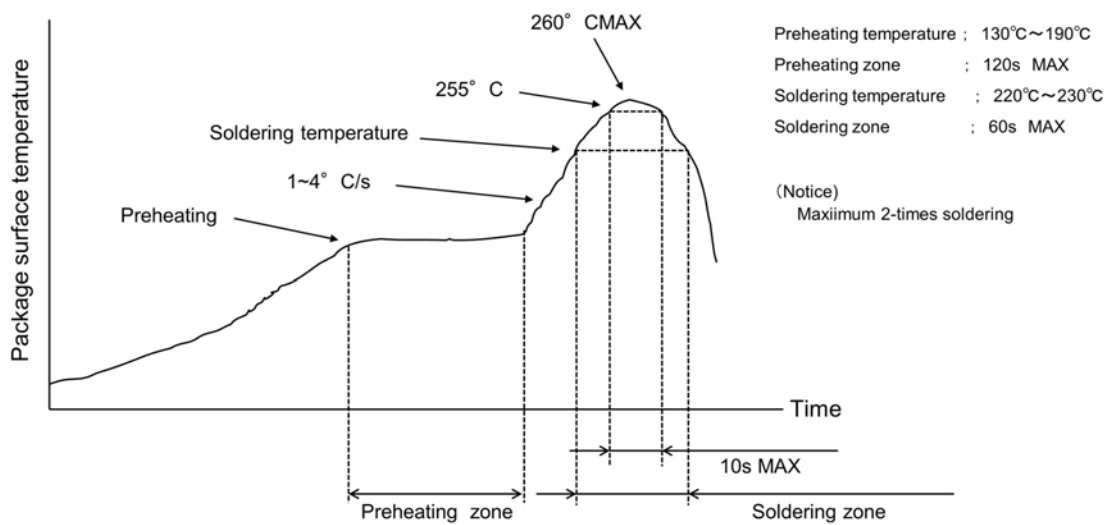
	Min.	Max.	Unit
Storage period	-	1	year

6.3 Drying process

Dryprocess is not required before solder mounting.

7. Soldering conditions

7.1 Recommended temperature profile for reflow



7.2 Recommended condition for wave soldering

Preheating temperature	:	120 °C to 150 °C
Preheating time	:	60 s MAX
Soldering temperature	:	260 °C ± 3 °C
Soldering time	:	12 s MAX

Notes for wave soldering

- (1) Soldering time is provided for total soldering time in case of dual wave soldering.
- (2) Do not use other soldering methods with wave soldering.
- (3) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (4) Optimize soldering condition to prevent solder bridging.
- (5) The heatsink may not be connected using wave soldering methods.

7.3 Recommended condition for solder iron

Solder iron temperature	:	380 °C or less
Mounting time	:	4 s or less

Notes for solder iron

- (1) The heatsink may not be connected using solder iron.
- (2) Solder mounting time is the time per 1 lead

Notes

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- 2) Before you use our Products, please contact our sales representative and verify the latest specifications :
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.
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- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
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